

**ABSTRACT**

A method of encapsulating an integrated-circuit component supported on a substrate comprises depositing on the component a thermally curable liquid organic matrix in sufficient quantity to form a layer covering the component. The liquid matrix layer is  
5 irradiated by laser radiation having a wavelength between about 600 and 1000 nanometers. The liquid matrix includes one or more additive materials that are strongly absorbing for the wavelength of the laser radiation. The liquid matrix layer is irradiated with the laser radiation for a time period sufficient to cure the matrix layer.